

COPPER-CLAD LAMINATE

ABSTRACT

5 There is provided a copper-clad laminate in which transmission characteristics exhibited by
a resin layer can be further improved while sufficient peel strength between a copper foil
and the resin layer is ensured. The laminate includes a copper foil; an adhesive layer
including a polyphenylene ether resin, a polyimide resin, an olefin-based resin, a liquid
crystal polymer, a polyester resin, a polystyrene resin, a hydrocarbon elastomer, a
10 benzoxazine resin, an active ester resin, a cyanate ester resin, a bismaleimide resin, a
butadiene resin, a hydrogenated or non-hydrogenated styrene butadiene resin, an epoxy
resin, a fluororesin, a vinyl-group-containing resin, or the like; and a resin layer. The
maximum height S_z at a copper foil surface on the adhesive layer side is $6.8\ \mu\text{m}$ or less.
The dielectric loss tangent value of the adhesive layer at 1 GHz, δ_a , is equal to or less than
15 that of the resin layer, δ_r .

No Suitable Figure